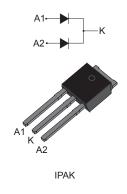


## 45 V power Schottky rectifier



#### **Features**

- · Very small conduction losses
- · Avalanche specification
- · Low forward voltage drop
- High frequency operation
- ECOPACK<sup>®</sup>2 compliant

### **Applications**

- DC/DC converter
- · Battery charger
- SMPS
- Desktop power
- Auxiliary power

### **Description**

This dual-diode common cathode Schottky rectifier is ideal for high frequency switch mode power supply.

Packaged in IPAK, the STPS2045CH is optimized for notebook, game station and desktop adapters, providing in these applications a good efficiency at both low and high load.

Product status link	
STPS2045CH	

Product summary		
I <sub>F(AV)</sub>	2 x 10 A	
V <sub>RRM</sub>	45 V	
V <sub>F</sub> (typ.)	0.50 V	
T <sub>j</sub> (max.)	175 °C	



#### 1 Characteristics

Table 1. Absolute ratings (limiting values, at 25 °C unless otherwise specified)

Symbol	Parameter			Value	Unit
$V_{RRM}$	Repetitive peak reverse voltage	Repetitive peak reverse voltage			V
I <sub>F(RMS)</sub>	Forward rms current			20	Α
,	A	T <sub>C</sub> = 155 °C	Per diode	10	
$I_{F(AV)}$ Average forward current $\delta$ = 0.5, square wave	Average forward current o = 0.5, square wave	T <sub>C</sub> = 150 °C	Per device	20	Α
I <sub>FSM</sub>	Surge non repetitive forward current $t_p = 10 \text{ ms sine-wave}$			150	Α
P <sub>ARM</sub>	Repetitive peak avalanche power $t_p$ = 10 $\mu$ s, $T_j$ = 125 $^{\circ}$ C			280	W
T <sub>stg</sub>	Storage temperature range			-65 to +175	°C
Tj	Maximum operating junction temperature (1)			+175	°C

<sup>1.</sup>  $(dP_{tot}/dT_j) < (1/R_{th(j-a)})$  condition to avoid thermal runaway for a diode on its own heatsink.

Table 2. Thermal resistance parameters

Symbol	Parameter	Value	Unit	
D.,	lunction to coop	Per diode	2.5	
R <sub>th(j-c)</sub> Junction to case	Total	1.6	°C/W	
R <sub>th(c)</sub>	Coupling		0.7	

For more information, please refer to the following application note:

• AN5088 : Rectifiers thermal management, handling and mounting recommendations

Table 3. Static electrical characteristics

Symbol	Parameter	Test conditions		Min.	Тур.	Max.	Unit
ı (1)	I <sub>R</sub> <sup>(1)</sup> Reverse leakage current	T <sub>j</sub> = 25 °C	$V_R = V_{RRM}$	-		100	μA
'R'		T <sub>j</sub> = 125 °C		-	7	15	mA
V <sub>F</sub> <sup>(2)</sup>	Forward voltage drop	T <sub>j</sub> = 125 °C	I <sub>F</sub> = 10 A	-	0.50	0.57	
		T <sub>j</sub> = 25 °C	I <sub>F</sub> = 20 A	-		0.84	V
		T <sub>j</sub> = 125 °C		-	0.65	0.72	

- 1. Pulse test:  $t_p = 5$  ms,  $\delta < 2\%$
- 2. Pulse test:  $t_p = 380 \ \mu s, \ \delta < 2\%$

To evaluate the conduction losses, use the following equation:

 $P = 0.42 \times I_{F(AV)} + 0.015 \times I_{F}^{2} (RMS)$ 

For more information, please refer to the following application notes related to the power losses :

- AN604: Calculation of conduction losses in a power rectifier
- AN4021: Calculation of reverse losses on a power diode

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### 1.1 Characteristics (curves)

Figure 1. Average forward power dissipation versus average forward current (per diode)

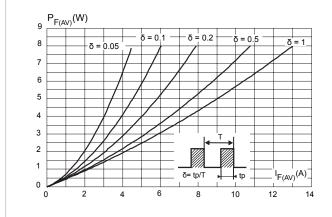


Figure 2. Average forward current versus ambient temperature ( $\delta$  = 0.5, per diode)

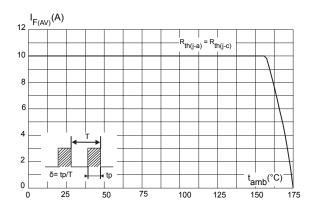


Figure 3. Normalized avalanche power derating versus pulse duration (T<sub>i</sub> = 125 °C)

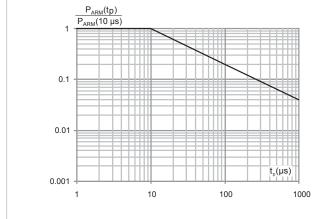
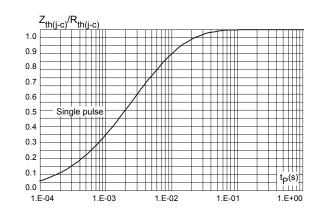


Figure 4. Relative variation of thermal impedance junction to case versus pulse duration



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Figure 5. Reverse leakage current versus reverse voltage applied (typical values, per diode) I<sub>R</sub>(μA) 1.E+05 1.E+04 T<sub>j</sub> = 125 °C 1.E+03 T<sub>j</sub> = 100 °C T<sub>j</sub> = 75 °C T<sub>i</sub>= 50 °C 1.E+01 1.E+00 T<sub>i</sub> = 25 °C  $V_{\mathsf{R}}(V)$ 1.E-01 0 10 25 30 35 40 45

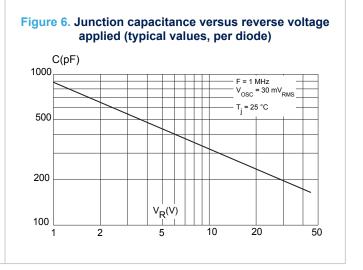
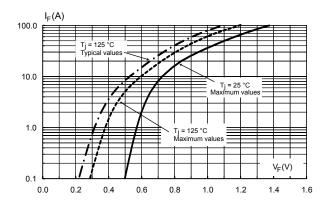


Figure 7. Forward voltage drop versus forward current (per diode)



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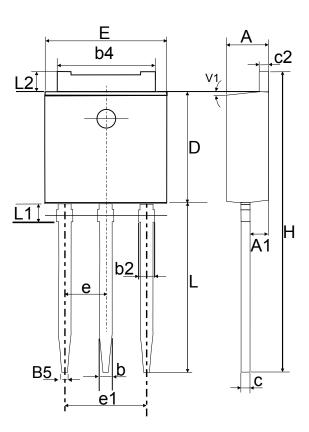
## Package information

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK® packages, depending on their level of environmental compliance. ECOPACK® specifications, grade definitions and product status are available at: www.st.com. ECOPACK® is an ST trademark.

### 2.1 IPAK package information

- Cooling method: by conduction (C)
- Epoxy meets UL 94,V0

Figure 8. IPAK package outline



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Table 4. IPAK package mechanical data

	Dimensions			
Ref.	Millin	neters	Incl	nes
	Min.	Max.	Min.	Max.
Α	2.20	2.40	0.087	0.094
A1	0.90	1.10	0.035	0.043
b	0.64	0.90	0.025	0.035
b2		0.95		0.037
b4	5.20	5.43	0.205	0.214
B5	0.30 typ.		0.012	typ.
С	0.45	0.60	0.018	0.024
c2	0.46	0.60	0.018	0.024
D	6.00	6.20	0.236	0.244
E	6.40	6.65	0.252	0.261
е	2.28 typ.		typ.0	.090
e1	4.40	4.60	0.173	0.181
Н	16.10 typ.		0.634 typ.	
L	9.0	9.60	0.354	0.378
L1	0.80	1.20	0.031	0.047
L2	0.80 typ.	1.25	0.031 typ.	0.049
V1	+10°		+10	

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# 3 Ordering information

**Table 5. Ordering information** 

Order code	Marking	Package	Weight	Base qty.	Delivery mode
STPS2045CH	S20 45CH	IPAK	0.31 g	75	Tube

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## **Revision history**

**Table 6. Document revision history** 

Date	Version	Changes
21-Jun-2012	1	First issue.
09-Oct-2014	2	Updated Table 2 and IPAK package informations.
27-Nov-2018	3	Removed figure 1 and figure 9.  Updated Table 1. Absolute ratings (limiting values, at 25 °C unless otherwise specified), Figure 5. Reverse leakage current versus reverse voltage applied (typical values, per diode), Figure 7. Forward voltage drop versus forward current (per diode) and Table 5. Ordering information.

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